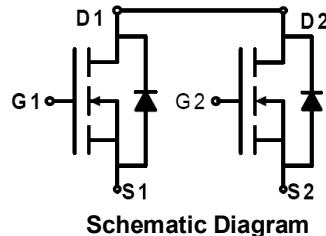


N-Channel Trench Power MOSFET

General Description

The CS8205G uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching applications.

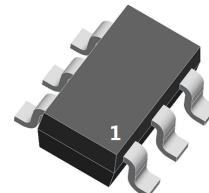
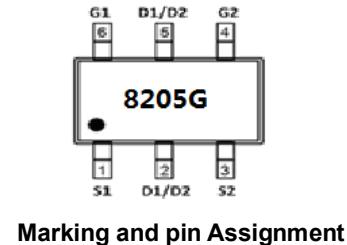


Features

- $V_{DS} = 19.5V, ID = 4.1A$
- $R_{DS(ON)} < 27m\Omega @ V_{GS} = 4.5V$
- $R_{DS(ON)} < 39m\Omega @ V_{GS} = 2.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

Application

- Battery protection
- Load switch
- Power management



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
8205G	CS8205G	SOT23-6	Ø180mm	8mm	3000 units

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	19.5	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 10	V
I_D	Drain Current-Continuous	4.1	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	25	A
P_D	Maximum Power Dissipation	1.14	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

Table 2. Thermal Characteristic

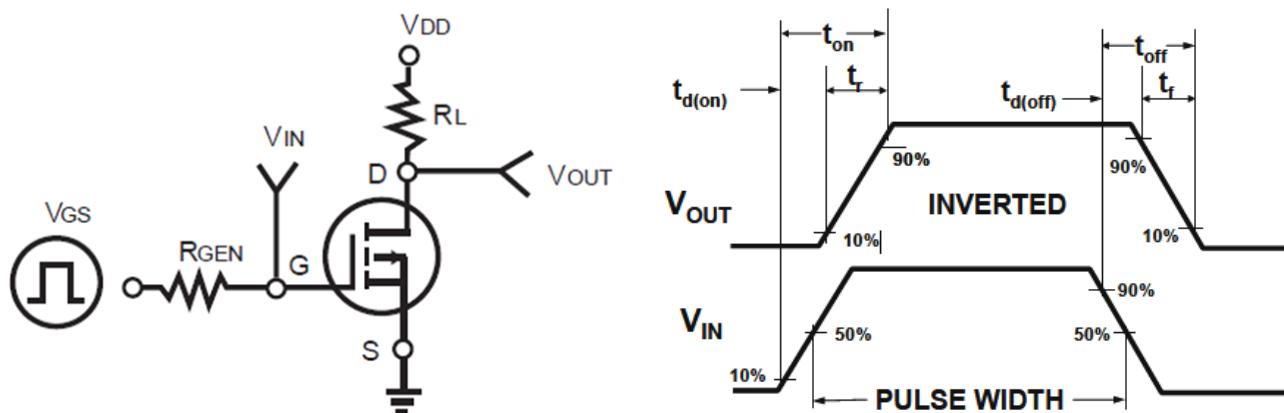
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	110	°C/W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	19.5	21		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =19V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5	0.7	1.1	V
g _{Fs}	Forward Transconductance	V _{DS} =5V, I _D =4.1A	4			S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =4.1A		21	28	mΩ
		V _{GS} =2.5V, I _D =3A		28	39	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =8V, V _{GS} =0V, f=1.0MHz		360		pF
C _{oss}	Output Capacitance			200		pF
C _{rss}	Reverse Transfer Capacitance			100		pF
Switching Times						
t _{d(on)}	Turn-on Delay Time	V _{DD} =10V, I _D =1A, V _{GS} =4.5V, R _G =6Ω		9		nS
t _r	Turn-on Rise Time			10		nS
t _{d(off)}	Turn-Off Delay Time			34		nS
t _f	Turn-Off Fall Time			29		nS
Q _g	Total Gate Charge	V _{DS} =10V, I _D =4A, V _{GS} =4.5V		8		nC
Q _{gs}	Gate-Source Charge			2.5		nC
Q _{gd}	Gate-Drain Charge			1.5		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current(Body Diode)				1.7	A
V _{SD}	Forward on Voltage ^(Note 1)	V _{GS} =0V, I _S =1.7A		0.79	1.2	V

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Switch Time Test Circuit and Switching Waveforms:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

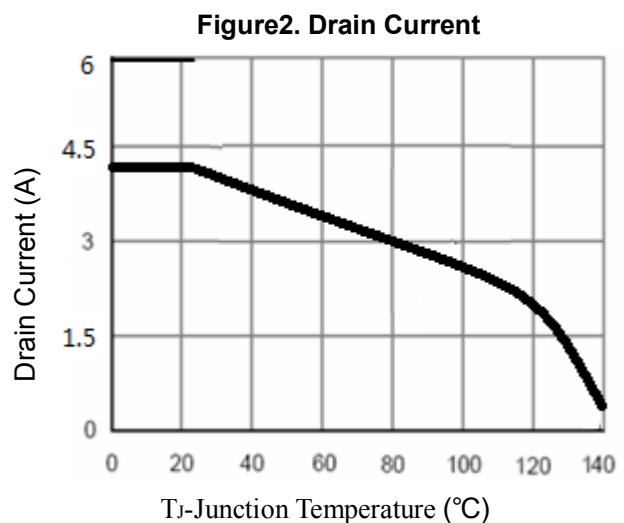
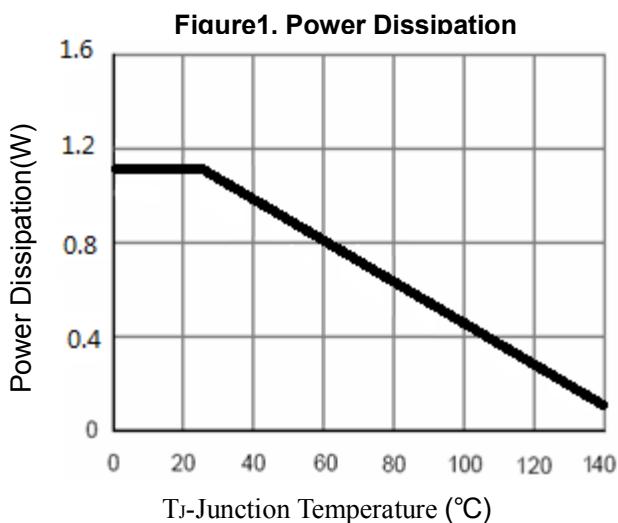


Figure3. Output Characteristics

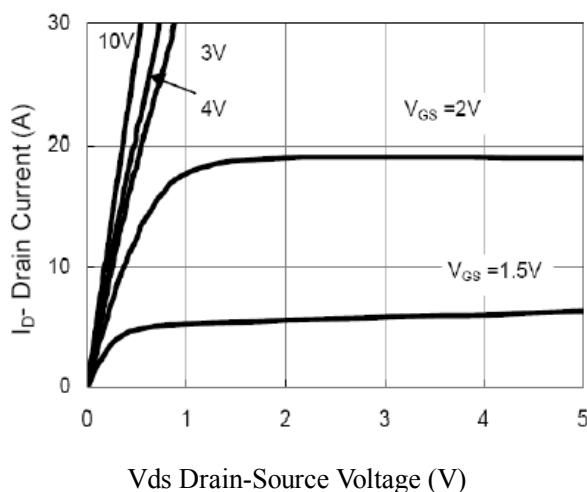


Figure4. Transfer Characteristics

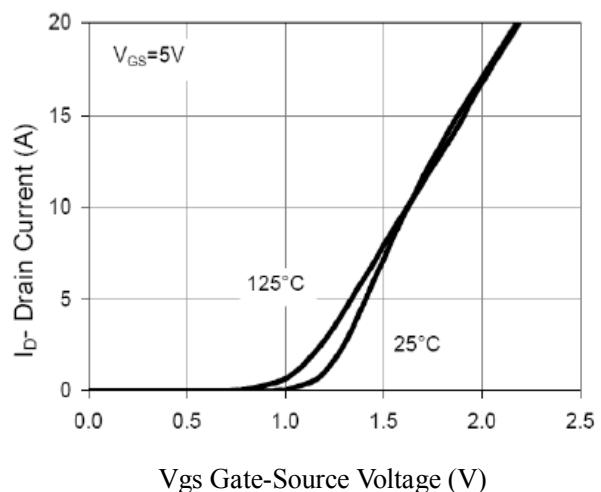


Figure5. Capacitance

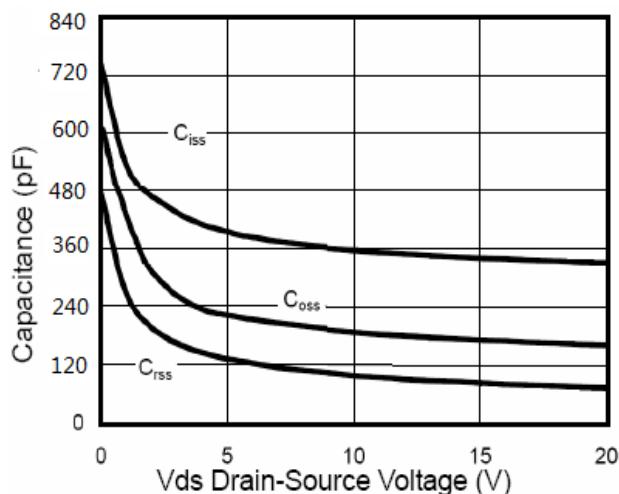


Figure6. $R_{DS(ON)}$ vs Junction Temperature

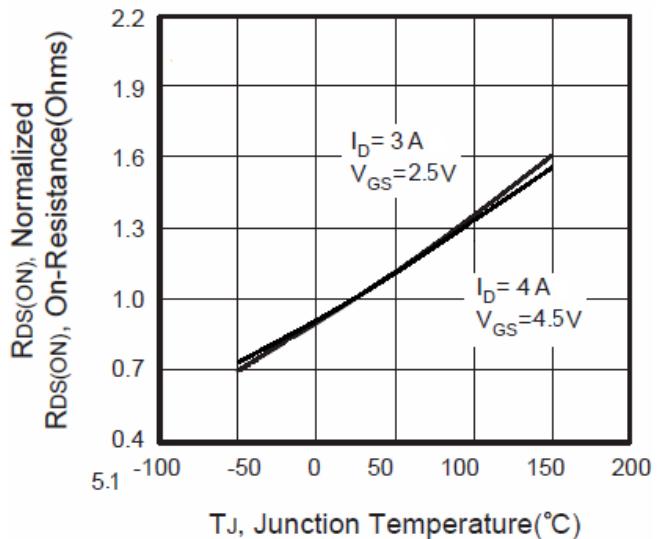


Figure7. Max BV_{DSS} vs Junction Temperature

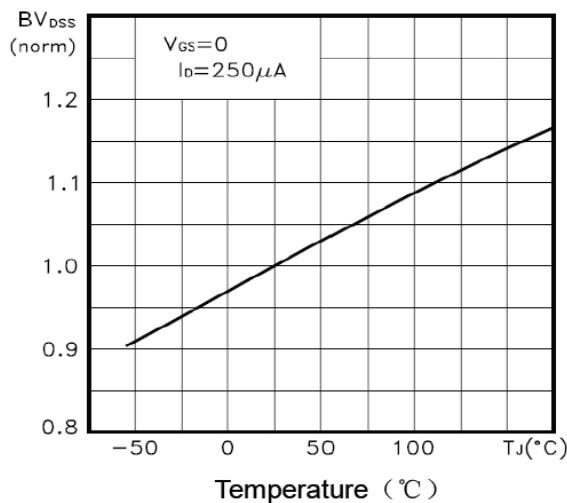


Figure8. $V_{GS(th)}$ vs Junction Temperature

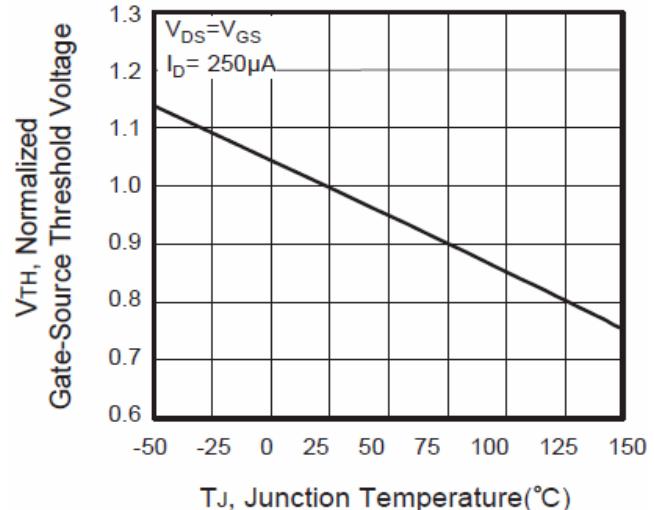


Figure9. Gate Charge Waveforms

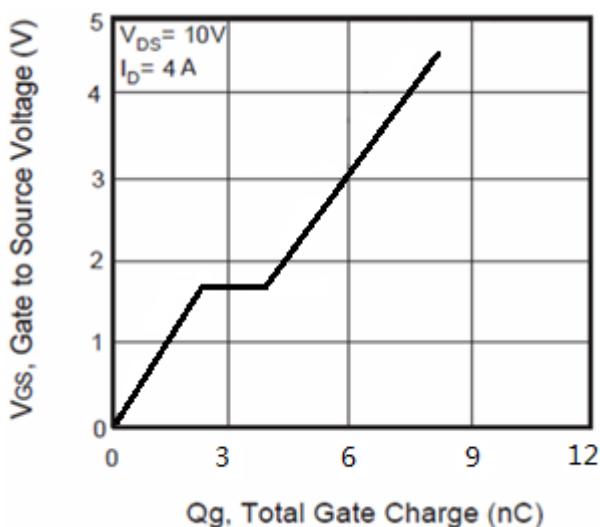


Figure10. Maximum Safe Operating Area

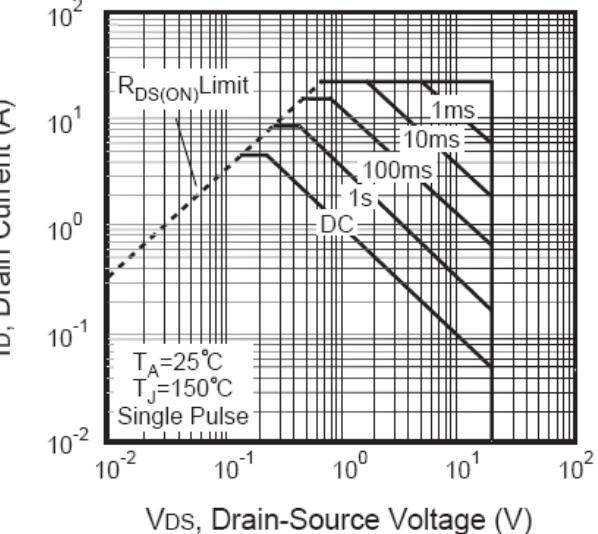
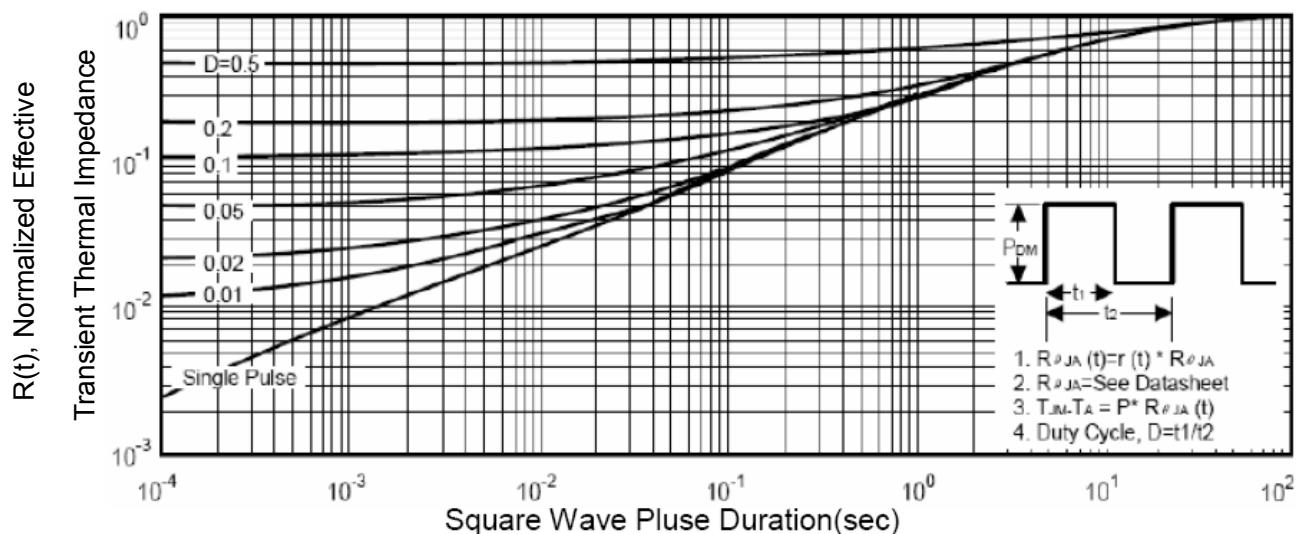
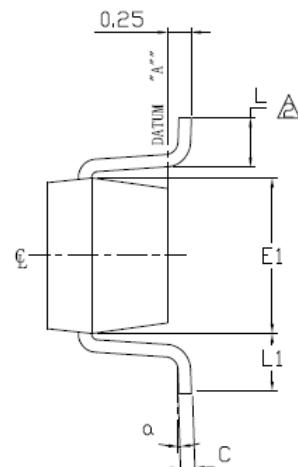
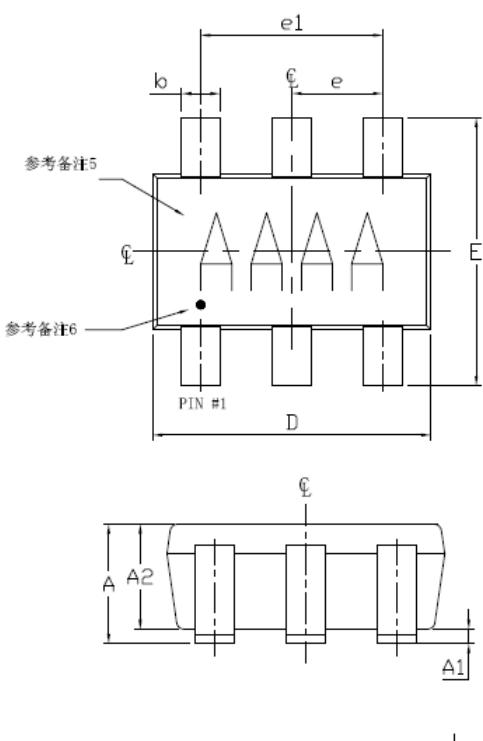


Figure11. Normalized Maximum Transient Thermal Impedance



SOT23-6 Package Information



SYMBOL	MIN	NOM	MAX
A	0.90	1.25	1.45
A1	0.00	0.05	0.15
A2	0.90	1.10	1.30
b	0.35	0.40	0.50
C	0.08	0.15	0.20
D	2.80	2.90	3.00
E	2.60	2.80	3.00
E1	1.50	1.625	1.75
L	0.35	0.45	0.60
L1	0.60	REF.	
e1	1.90	BSC.	
e	0.95	BSC.	
α	0°	2.5°	8°

PKG CODES:
U6-1, U6-2, U6-4, U6CN-2,
U6SN-1, U6F-6, U6FH-6

- 备注:
- 标注单位:MM.
 - 引脚长度的测量点为引脚与塑封体接触点及引脚边缘最长处。3. 塑封体测量尺寸不包括毛刺及金属毛刺，另塑封体毛刺及金属毛刺长度不超过0.25mm。
 - 引脚平面度控制小于0.1mm。
 - 印字面向上进行读取时，PIN1 位于左下方（参考图解）。
 - PIN1的标记最小为 $\varnothing 0.3$ mm，并位于PIN1脚位上方。
 - 考文献: JEDEC TO236-VARIATION AB.